


Stellar SR6 P3 line—32-bit Arm® Cortex®-R52+ automotive integration MCU  
 3× Cortex®-R52+ cores, 8 MB NVM (2× 7.5 MB “OTA X2”)  
 1.3 MB RAM, with embedded virtualization, safety, and security



FPBGA292  
(17 × 17 mm)



## Features

- AEC-Q100 
- SR6 integration *MCUs*:
  - Have superior real-time and safe performance (with highest *ASIL-D* capability)
  - Bring hardware-based virtualization technology to *MCUs* for simplified multiple software integrations at optimized performance
  - Have built-in fast and cost-effective *OTA* reprogramming capability (with built-in dual-image storage)
  - Offer high-speed security cryptographic services, for example for network authentication

## Cores

- 3 × 32-bit Cortex®-R52+ cores (all of them in lockstep configuration):
  - Arm® v8-R compliant
  - Single precision floating-point unit (*FPU*)
  - New privilege level for real-time virtualization
- 2 Cortex®-M4 multipurpose accelerators, one in lockstep configuration
- 4 *eDMA* engines in lockstep configuration

## Memories

- Up to 8 MB on-chip nonvolatile memory (NVM):
  - PCM (phase-change memory) as nonvolatile memory
  - 7.5 MB code NVM, with embedded memory replication for *OTA* (over-the-air) reprogramming with up to 2× 7.5 MB
  - 512 KB HSM-dedicated code NVM
- 256 KB data NVM (128 KB + 128 KB dedicated to HSM)
- Up to 1328 KB on-chip general-purpose SRAM

Product summary	
Part number	Package
SR6P3C4	FPBGA292

**Security: 2<sup>nd</sup> generation hardware security module**

- Cybersecurity: ISO/SAE 21434 compliance (refer to the cybersecurity reference manual for details)
- On-chip high-performance security module with full support for e-safety vehicle intrusion protected applications (EVITA)
- Symmetric and asymmetric cryptography processor
- High-performance lock-stepped AES-light security subsystem for fast ASIL-D cryptographic services

**Safety: comprehensive new-generation ASIL-D safety concept**

- New state-of-the-art safety measures at all levels of the architecture for most efficient implementation of ISO 26262 ASIL-D functionalities
- Complete hardware virtualization architecture built on Cortex<sup>®</sup>-R52+ new privilege mode (best-in-class software isolation, real-time support for multiple virtual machines/applications)

**Peripheral, I/O, and communication interfaces**

- 16 LINFlexD modules
- 1 dual-channel FlexRay controller
- 10 queued serial peripheral interface (SPIQ) modules
- 2 microsecond channels (MSC) and 1 microsecond plus (MSC-Plus) channel
- 2 I<sup>2</sup>C interfaces
- 2 SENT modules (10 channels each)
- 2 PSI5 modules (1 channel each)
- Enhanced analog-to-digital converter system with:
  - 6 separate 12-bit SAR analog converters (including one supervisor/safety ADC).
  - 4 separate 9-bit SAR analog converters (2 channels each) with fast comparator mode
  - 6 separate 16-bit sigma-delta analog converters with embedded DSP processor on each SD ADC
  - Enhanced interconnection with GTM timer for autonomous ADC/GTM subsystem operation
- Advanced timed I/O capability:
  - Generic timer module (GTM4124)
  - High-resolution timer
- Communication interfaces:
  - One 10/100/1000 Mbit/s Ethernet controller compliant with IEEE 802.3-2008: IPv4 and IPv6 checksum modules, AVB, VLAN
  - 7 modular controller area network (MCAN) modules, and 1 time-triggered controller area network (M\_TTCAN), all supporting flexible data rate (ISO CAN FD<sup>®</sup>)
  - 2 CAN XL<sup>®</sup> interfaces

# 1 Introduction

## 1.1 Document overview

This document provides a summary of the target specification and features of the SR6P3C4 devices. For detailed information, refer to the device Datasheet and device Reference manual.

*Note:* For information on the Cortex®-R52+ and Cortex®-M4 cores, refer to the technical reference manuals, available from the [www.arm.com](http://www.arm.com) website.

*Note:* Arm and the Arm logo are registered trademarks of Arm Limited (or its subsidiaries) in the US and/or elsewhere.



## 1.2 Description

Stellar integration MCUs have been designed to meet the requirements of domain controllers and ECUs with high integration requested in the architectures of connected updatable automated and electrified cars. They have superior real-time and safe performance (with highest ASIL-D capability). Bringing hardware-based virtualization technology to MCUs, they ease the development and integration of multiple source software onto the same hardware while maximizing the resulting software performance. They offer high-efficiency OTA reprogramming capability with fast new image download and activation at almost no memory overhead thanks to SR6 unique built-in dual-image storage tailored to OTA reprogramming needs. They also provide high-speed security cryptographic services, for instance for network authentication.

**Table 1. SR6P3C4 overview**

Feature		SR6P3C4
Cortex®-R52+ cores (+ checker cores)		3 cores (+3 checkers)
Neon™ (with SIMD, dual precision floating point)		No
Cache (instruction/data) per core in Kbyte		16/8
Core memory protection unit (regions), several additional protection mechanisms in the architecture, for example: NOC firewalls	Hypervisor (EL2)	24
	OS (EL1)	24
Code NVM	Overall including HSM in Mbytes	8
	Cluster code NVM in Mbytes	7.5
	HSM code NVM in Kbytes	512
Code NVM built-in memory replication for OTA reprogramming (not supported by HSM) in Mbytes		Up to 2× 7.5
Data NVM in Kbytes		256
RAM in Kbytes		1328
Hardware security module (HSM) - 2 <sup>nd</sup> generation		Yes
AES-Light (cryptographic services)		2
Arm® Cortex®-M4	Multipurpose accelerator (DSPH)	1
	Multi-purpose accelerator in lockstep (DME)	1
eDMA engines (number of channels, more channels through muxes/channel)	Engine	4
	Channel	4× 32
LIN and UART (LINFlexD)		16
CAN_FD		8
CAN_XL		2
SPIQ (with LVDS channel)		10 (2)
Microsecond channel (MSC)		2

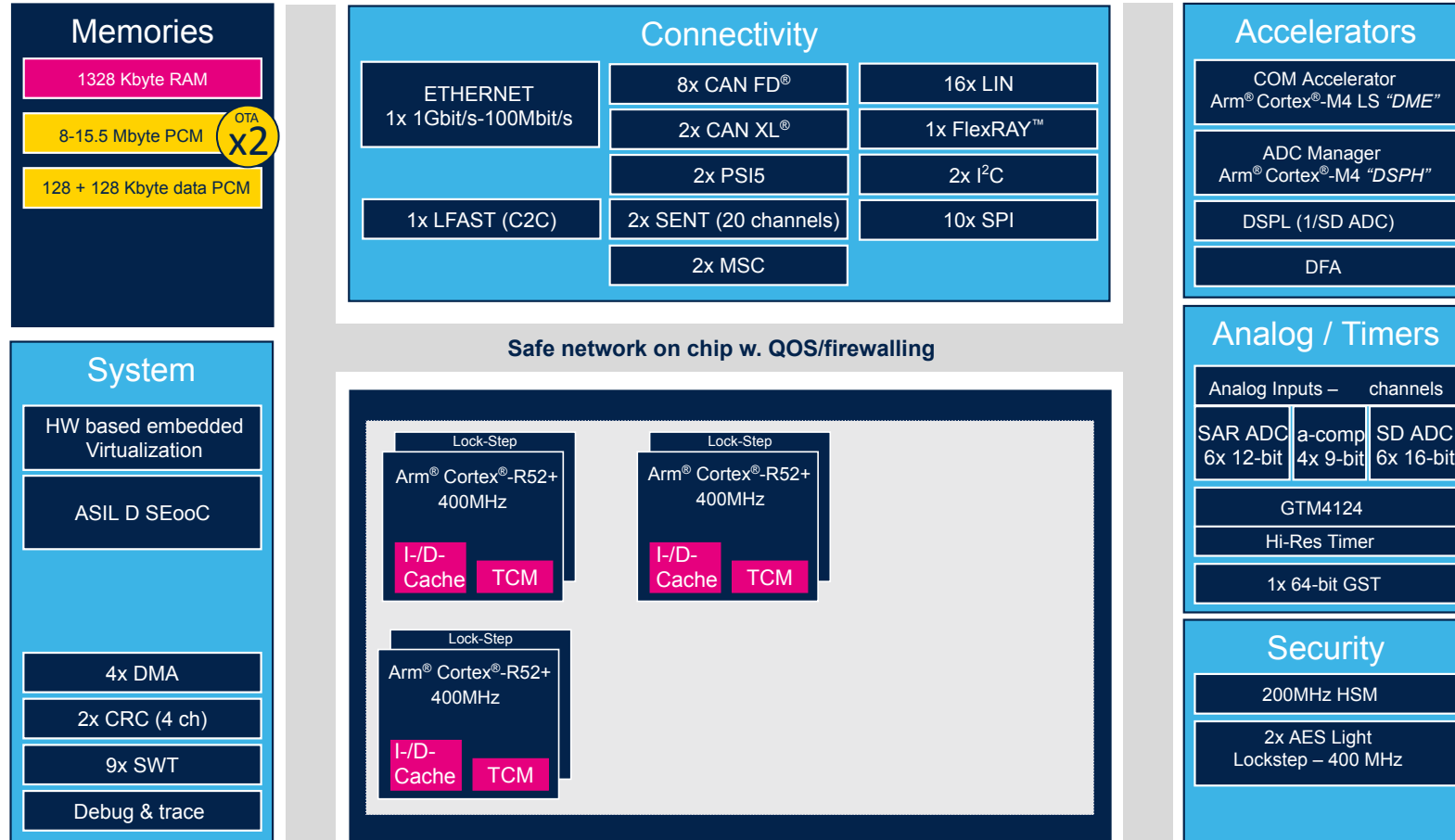
Feature		SR6P3C4
SENT	Unit	2
	Channel/unit	10
I <sup>2</sup> C		2
PSI5	Unit	2
	Channel/unit	1 channel
FlexRay™ (dual channel)		1
Gigabit ethernet IEEE 802.3-2008 compliant	Total	1
	With MII, RMII, RGMII, and SGMII	0
	With MII, RMII, and RGMII	1
	With RMII and SGMII	0
SIPI/LFAST interprocessor bus		1
Generic timer modules (GTM4)		GTM4124
High-resolution timer		2 × 8 ch
12-bit SAR analog converters		6
16-bit sigma-delta analog converters (units with DSPL)		6
9-bit SAR analog comparators		8
Octo-SPI (support HyperBus™ memory devices)		No
Debug port	Main debug port (JTAG+SWD)	Yes
	Secondary debug port (SWD)	Yes
High-speed off-chip trace lane (multi GBit/s, Aurora™ protocol)		2
Max temperature (target)	Junction temperature	165 °C <sup>(1)</sup>
Packages	FPBGA516	—
	FPBGA476	—
	FPBGA292	X

1. Nominal specification up to 150 °C. Delta specification up to 165 °C.

### 1.3 Block diagram

The figure below shows the top-level block diagram.

Figure 1. Block diagram



## Revision history

**Table 2. Document revision history**

Date	Version	Changes
22-Oct-2024	1	Initial release.

## Glossary

- ADC** Analog-to-digital converter
- AEC** Automotive Electronics Council. Also known as CDF-AEC for Chrysler-Delco-Ford Automotive Electronics Council. Shortened to AEC.
- AES** Advanced encryption standard. Cryptographic algorithm.
- ASIL** Automotive safety integrity level  
It is a risk classification system defined by the ISO 26262 standard for the functional safety of road vehicles. There are four ASILs identified by ISO 26262—A, B, C, and D. ASIL A represents the lowest degree and ASIL D represents the highest degree of automotive hazard.
- AVB** Audio-video bridging
- BCS** Boot code sector
- BSC** Basic (dimension)
- CAN** Controller area network
- CAN FD**<sup>®</sup> Controller area network flexible data rate
- CAN XL**<sup>®</sup> Controller area network extra long
- CBC** Cipher block chaining
- CDM** Charged device model
- CFB** Cipher feedback
- CGM** Clock generation module
- CMAC** Cipher-based message authentication code
- CMD** Command
- CMOS** Complementary metal-oxide-semiconductor
- COL** Collision detect  
Asynchronous receiver signal of the media-independent interface (MII).
- CPHA** Clock phase bit. Selects the clock phase.
- CPOL** Clock polarity bit. Selects the clock polarity.
- CPU** Central processing unit
- CRC** Cyclic redundancy check
- CRS** Carrier sense  
Asynchronous receiver signal of the media-independent interface (MII).
- CTI** Arm<sup>®</sup> CoreSight<sup>™</sup> cross-trigger interface
- CTM** Cross-trigger matrix
- CTR** Counter mode
- CXPI** Clock extension peripheral interface
- DAC** Digital-to-analog converter
- DC** Direct current
- DCF** Device configuration format
- DDR** Double data rate
- DMA** Direct memory access
- DME** Data movement engine
- DNL** Differential nonlinearity
- DSP** Digital signal processing
- eDMA** Enhanced direct memory access
- EMC** Electromagnetic compatibility
- EVITA** e-safety vehicle intrusion protected applications
- FCCU** Fault collection and control unit
- FPBGA** Fine-pitch-ball-grid-array
- FPU** Floating-point unit
- GB** Gigabyte
- GPIO** General-purpose input/output

<b>GTM</b> Generic timer module	<b>OS</b> Operating system
<b>HSM</b> Hardware security module	<b>OSR</b> Oversampling ratio
<b>HSSTP</b> High-speed serial trace probe	<b>OTA</b> Over the air
<b>I/O</b> Input/output	<b>PHY</b> Physical layer
<b>IEC</b> International Electrotechnical Commission	<b>PLL</b> Phase-locked loop
<b>IEEE</b> Institute of Electrical and Electronics Engineers	<b>PSI5</b> Peripheral sensor interface (PSI5). An interface for automotive sensor applications.
<b>IPv4</b> Internet protocol version 4	<b>RAM</b> Random access memory
<b>IPv6</b> Internet protocol version 6	<b>RGMII</b> Reduced gigabit media-independent interface
<b>ISO</b> International Organization for Standardization	<b>RMII</b> Reduced media-independent interface
<b>I<sup>2</sup>C</b> Inter-integrated circuit	<b>SAR</b> Successive approximation register
<b>JEDEC</b> Joint Electron Device Engineering Council	<b>SENT</b> Single-edge nibble transmission for automotive applications
<b>JTAG</b> Joint Test Action Group	<b>SeooC</b> Safety element out of context
<b>KB</b> Kilobyte	<b>SIMD</b> Single-instruction multiple data
<b>LFAST</b> LVDS fast asynchronous serial transmit interface	<b>SIPI</b> Serial interprocessor interface
<b>LIN</b> Local interconnect network	<b>SPI</b> Serial peripheral interface
<b>LVDS</b> Low-voltage differential signaling	<b>SPIQ</b> Queued serial peripheral interface
<b>M_TTCAN</b> Time-triggered controller area network	<b>SRAM</b> Static random-access memory
<b>MB</b> Megabyte	<b>SRC</b> Sample rate converter
<b>MCAN</b> Modular controller area network	<b>ST</b> STMicroelectronics
<b>MCU</b> Microcontroller unit	<b>STLA</b> Signal tap logic analyzer
<b>MEMU</b> Memory error management unit	<b>SWD</b> Secondary debug port
<b>MII</b> Media-independent interface	<b>UART</b> Universal asynchronous receiver/transmitter
<b>MSC</b> Microsecond channel	<b>VLAN</b> Virtual local area network
<b>NoC</b> Network on chip	
<b>NVM</b> Nonvolatile memory	



**IMPORTANT NOTICE – READ CAREFULLY**

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgment.

The product must not be used following exposure greater than or equal to a total ionizing dose of 50 krad per silicon for military applications, or for commercial space applications at altitudes above 50 000 feet.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, refer to [www.st.com/trademarks](http://www.st.com/trademarks). All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2024 STMicroelectronics – All rights reserved